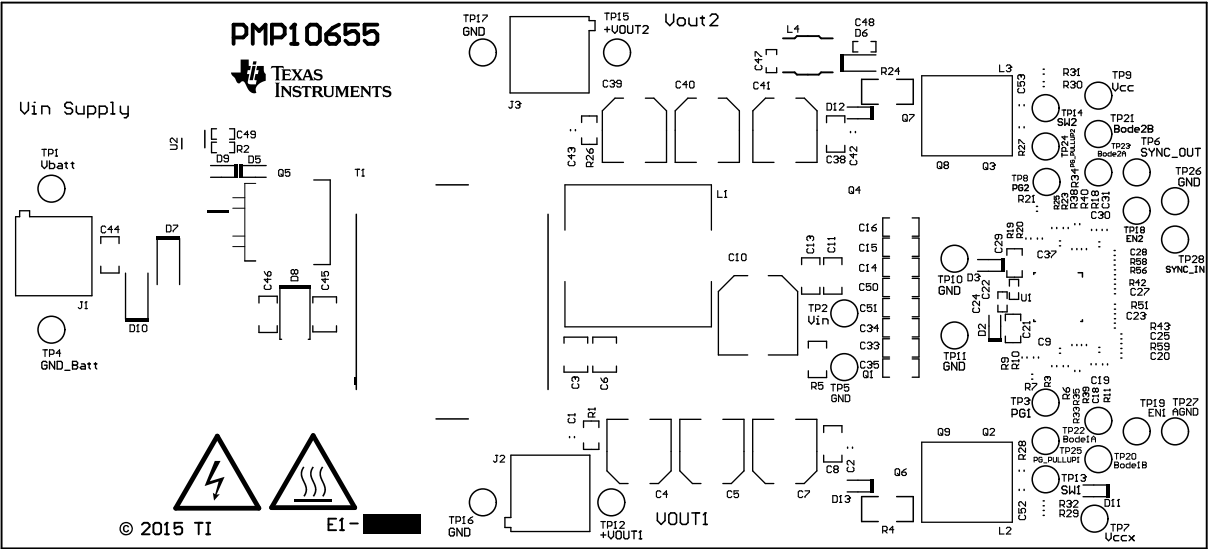
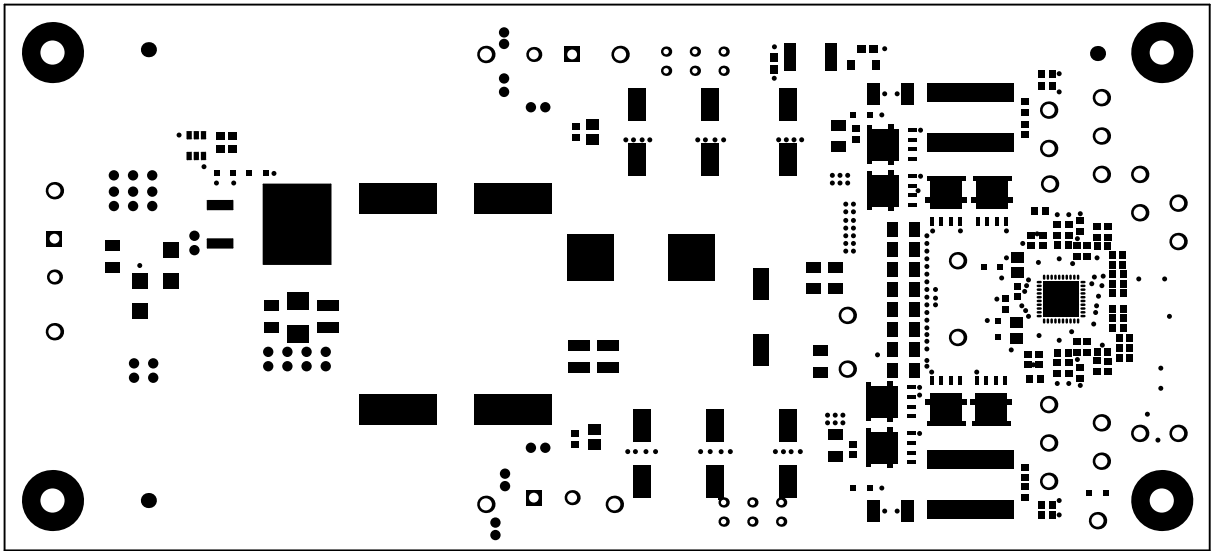
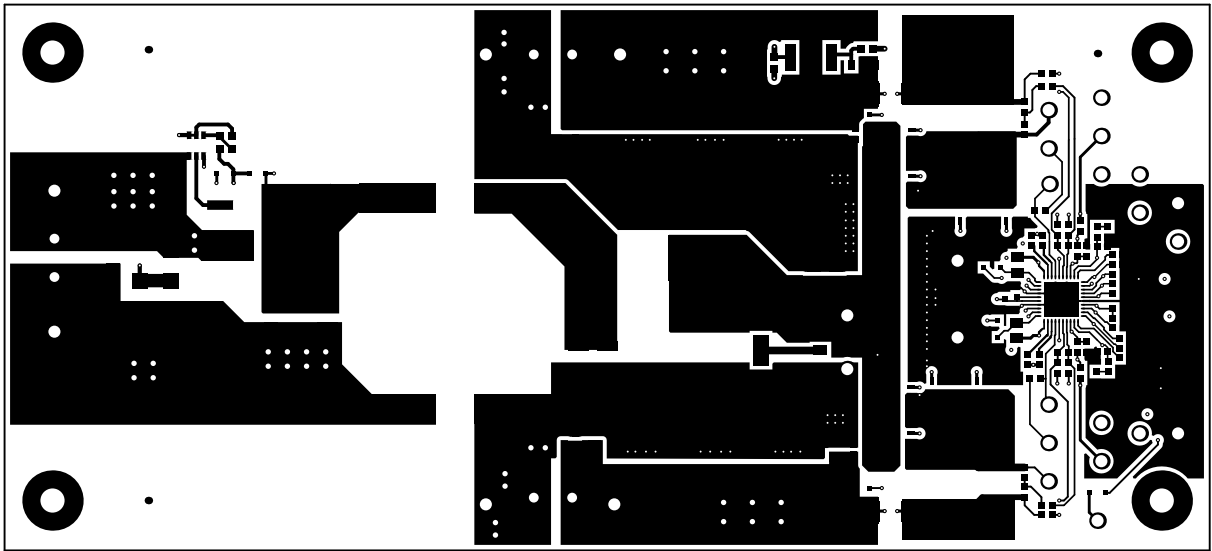


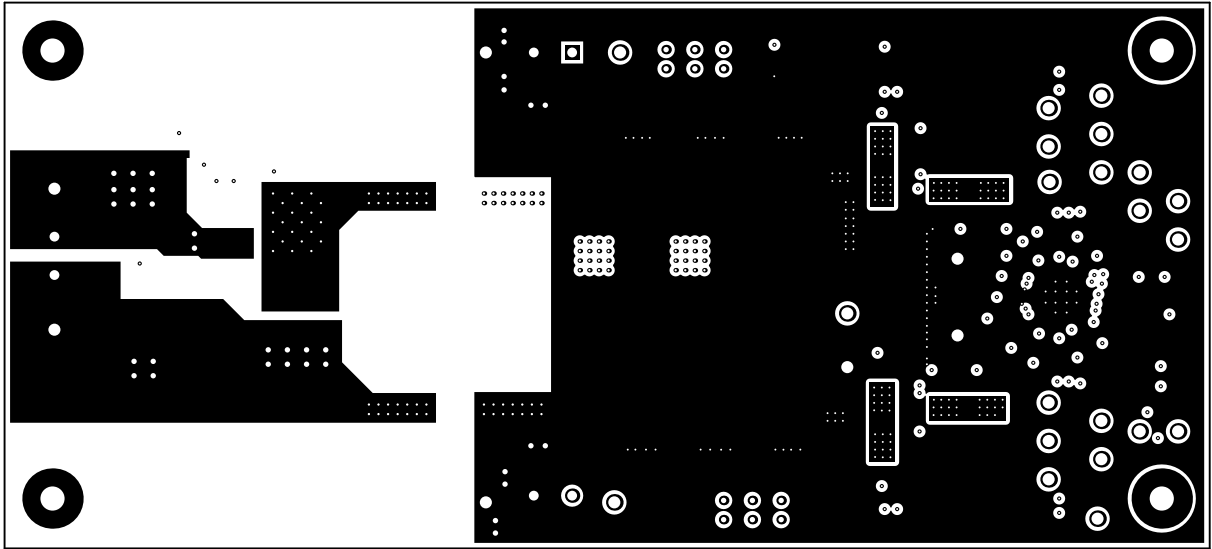




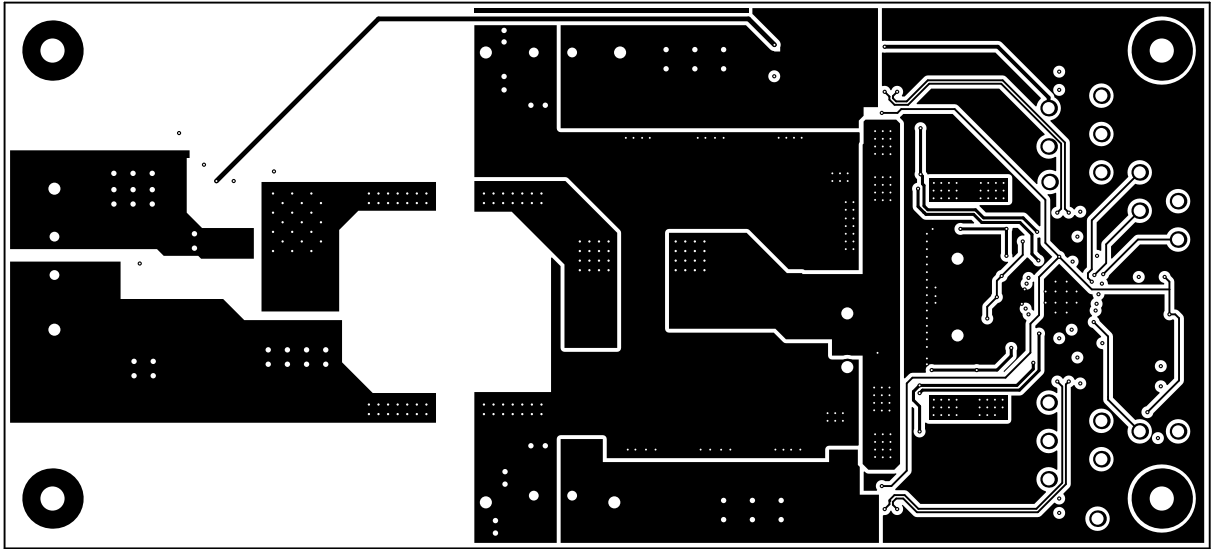
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP10655		
PLOT NAME = Top Solder Mask	GENERATED : 11/30/2017 3:47:51 PM		TEXAS INSTRUMENTS



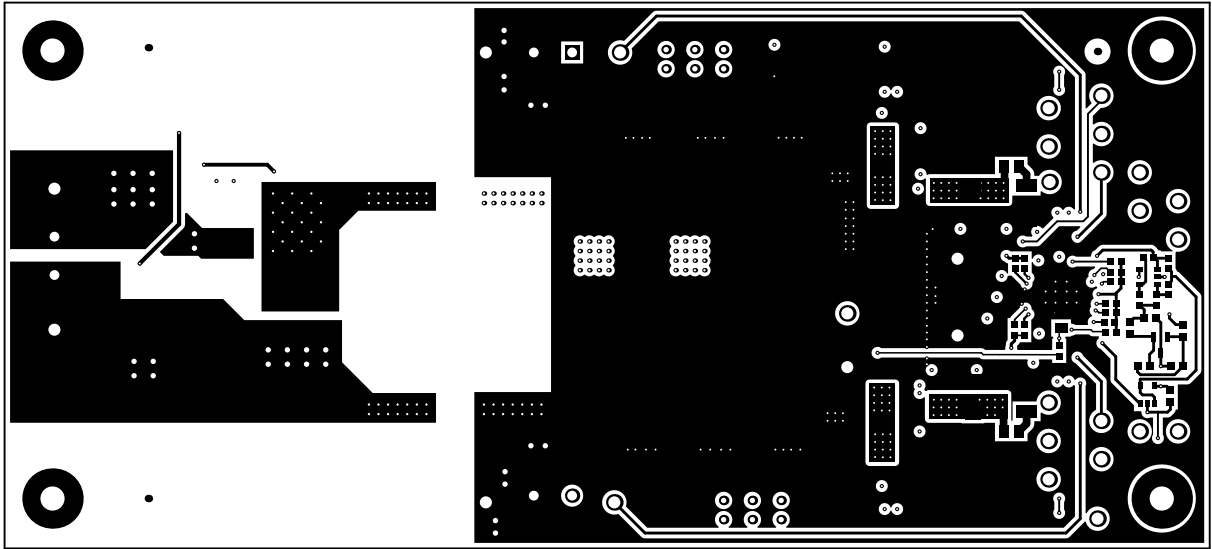
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP10655		
PLOT NAME = Top Layer	GENERATED : 11/30/2017 3:47:52 PM		TEXAS INSTRUMENTS



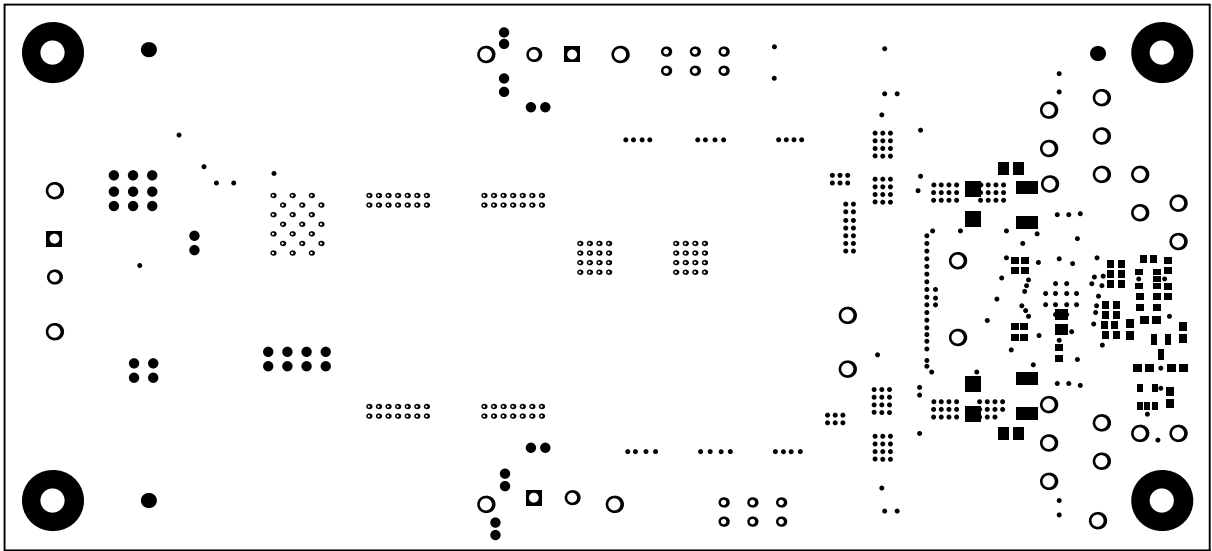
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP10655		
PLOT NAME = Signal Layer 1	GENERATED : 11/30/2017 3:47:52 PM		TEXAS INSTRUMENTS



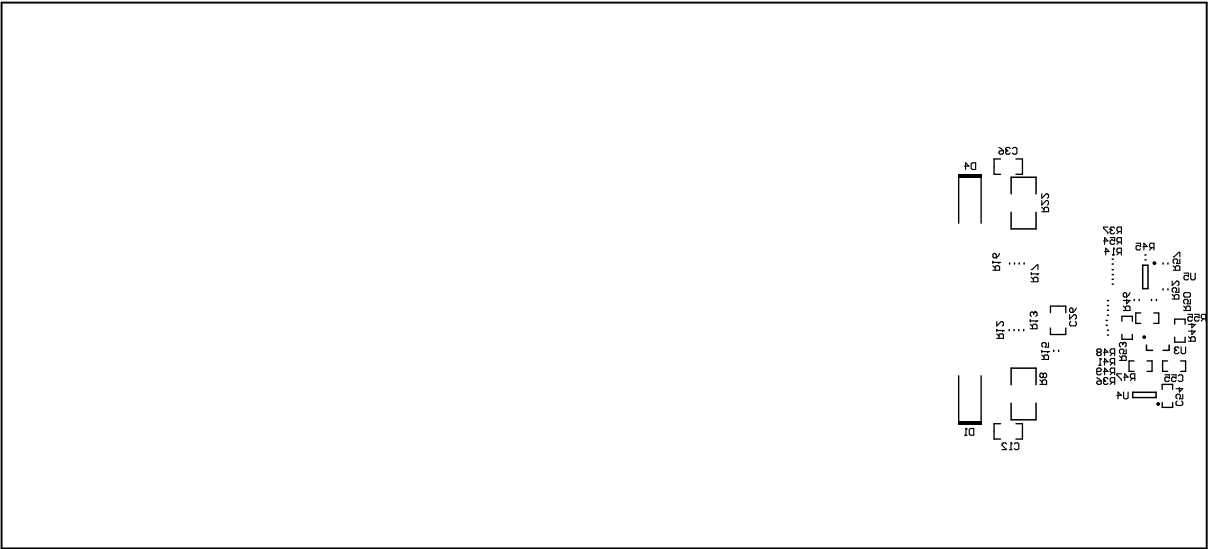
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP10655		
PLOT NAME = Signal Layer 2	GENERATED : 11/30/2017 3:47:53 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP10655		
PLOT NAME = Bottom Layer	GENERATED : 11/30/2017 3:47:54 PM		TEXAS INSTRUMENTS

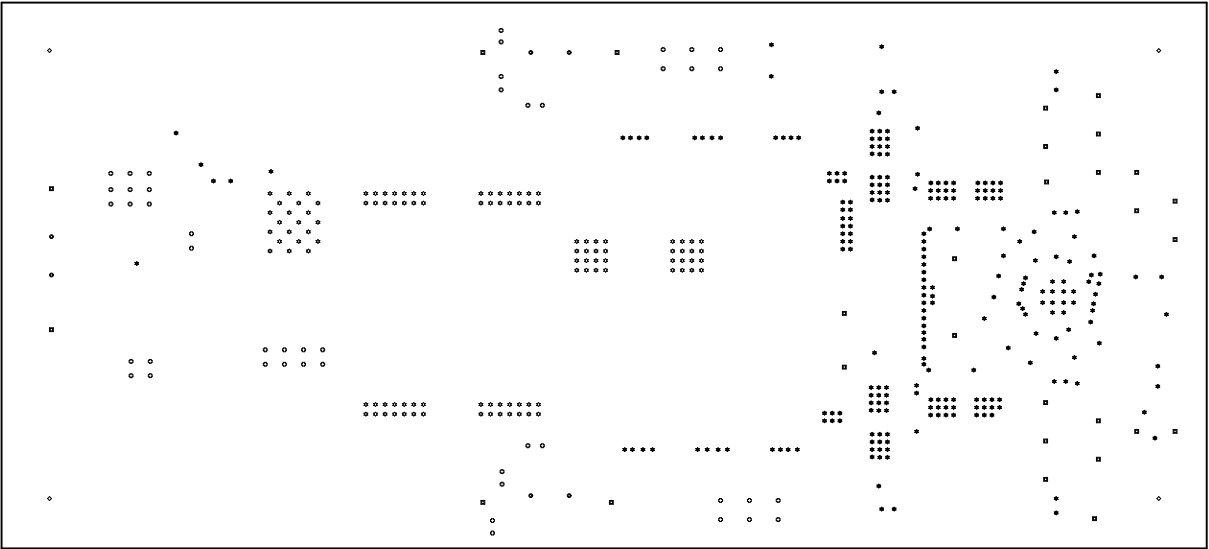


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP10655	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME = Bottom Solder	TID #:	PMP10655				
PLOT NAME = Bottom Solder Mask	GENERATED	: 11/30/2017 3:47:54 PM			TEXAS INSTRUMENTS	

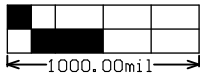
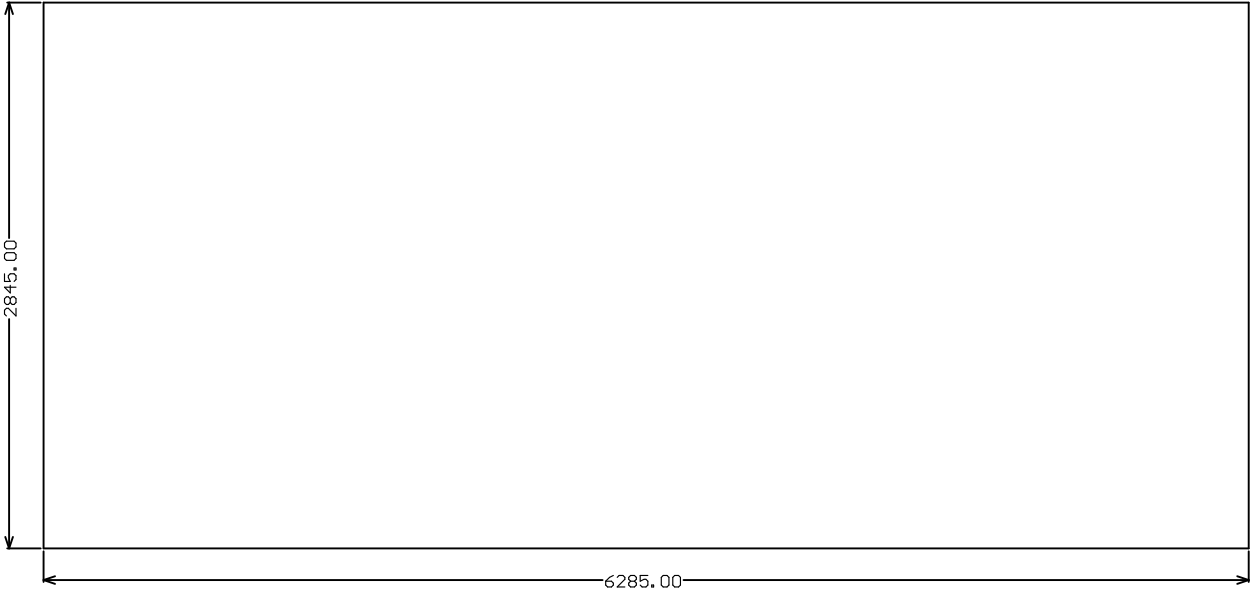


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP10655		
PLOT NAME = Bottom Overlay	GENERATED : 11/30/2017 3:47:55 PM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✳	254	10.00mil (0.254mm)	PTH	Round
⚙	109	12.00mil (0.305mm)	PTH	Round
⚙	47	28.00mil (0.711mm)	PTH	Round
⦿	6	51.18mil (1.300mm)	PTH	Round
■	28	63.00mil (1.600mm)	PTH	Round
◊	4	125.98mil (3.200mm)	PTH	Round
448 Total				



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP10655		
PLOT NAME = Drill Drawing	GENERATED : 11/30/2017 3:47:56 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP10655	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:	PMP10655				
PLOT NAME = Board Dimensions	GENERATED	: 11/30/2017 3:47:58 PM			TEXAS INSTRUMENTS	

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